

### Is Now Part of



# ON Semiconductor®

# To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer

www.onsemi.com

#### ON Semiconductor®



# FDS4141

# P-Channel PowerTrench<sup>®</sup> MOSFET -40V, -10.8A, 13.0m $\Omega$

#### **Features**

- Max  $r_{DS(on)} = 13.0 \text{m}\Omega$  at  $V_{GS} = -10 \text{V}$ ,  $I_D = -10.5 \text{A}$
- Max  $r_{DS(on)} = 19.0 \text{m}\Omega$  at  $V_{GS} = -4.5 \text{V}$ ,  $I_D = -8.4 \text{A}$
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- RoHS Compliant

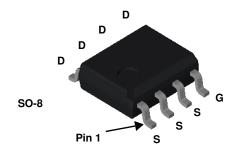


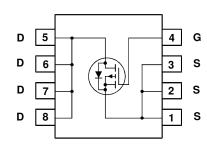
#### **General Description**

This P-Channel MOSFET has been produced using On Semiconductor's proprietary PowerTrench<sup>®</sup> technology to deliver low  $r_{DS(on)}$  and optimized BV<sub>DSS</sub> capability to offer superior performance benefit in the applications and optimized switching performance capability reducing power dissipation losses in converter/inverter applications.

#### **Applications**

- Control switch in synchronous & non-synchronous buck
- Load switch
- Inverter





## MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V <sub>DS</sub>	Drain to Source Voltage		-40	V	
$V_{GS}$	Gate to Source Voltage		±20	V	
	Drain Current -Continuous		-10.8		
'D	-Pulsed		-36	A	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	294	mJ	
В	Power Dissipation T <sub>A</sub> = 25°C	(Note 1a)	5	W	
$P_{D}$	Power Dissipation T <sub>A</sub> = 25°C	(Note 1b)	2.5	VV	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C	

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS4141	FDS4141	SO-8	13"	12mm	2500units

# **Electrical Characteristics** $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25°C		-33		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -32V$ ,			-1	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = -250\mu A$	-1.0	-1.6	-3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = -250μA, referenced to 25°C		5.3		mV/°C
		$V_{GS} = -10V, I_D = -10.5A$		11.0	13.0	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = -4.5V, I_D = -8.4A$		15.2	19.0	mΩ
		$V_{GS} = -10V, I_D = -10.5A, T_J = 125$ °C		16.8	19.9	
g <sub>FS</sub>	Forward Transconductance	$V_{DD} = -5V, I_{D} = -10.5A$		37		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz	2005	2670	pF
C <sub>oss</sub>	Output Capacitance		355	475	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		190	285	pF
$R_g$	Gate Resistance	f = 1MHz	5		Ω

## **Switching Characteristics**

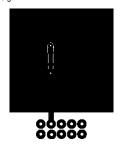
t <sub>d(on)</sub>	Turn-On Delay Time		10	20	ns
t <sub>r</sub>	Rise Time	$V_{DD} = -20V, I_D = -10.5A,$	5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = -10V, R_{GEN} = 6\Omega$	42	68	ns
t <sub>f</sub>	Fall Time		12	22	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0V to -10V	35	49	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0V \text{ to -5V}$ $V_{DD} = -20V,$	19	27	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = -10.5A	6		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		7		nC

#### **Drain-Source Diode Characteristics**

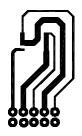
V <sub>SD</sub> Source to Drain Diode Forward Voltage	Source to Drain Diode Ferward Voltage	$V_{GS} = 0V, I_S = -10.5A$ (Note 2)	-0.8	-1.3	V
	$V_{GS} = 0V, I_S = -2.1A$ (Note 2)	-0.7	-1.2	V	
t <sub>rr</sub>	Reverse Recovery Time	- I <sub>E</sub> = -10.5A, di/dt = 100A/μs	26	42	ns
Q <sub>rr</sub>	Reverse Recovery Charge	- 1F = -10.5A, αι/αι = 100A/μS	14	26	nC

#### NOTES

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a) 50°C/W when mounted on a 1in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width <  $300\mu\text{s},$  Duty cycle < 2.0%.
- 3. UIL condition: Starting  $T_J$  = 25°C, L = 3mH,  $I_{AS}$  = -14A,  $V_{DD}$  = -40V,  $V_{GS}$  = -10V.

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

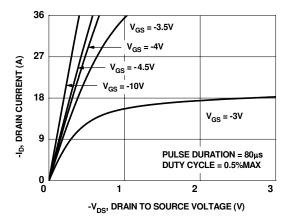


Figure 1. On-Region Characteristics

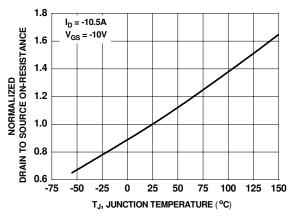


Figure 3. Normalized On-Resistance vs Junction Temperature

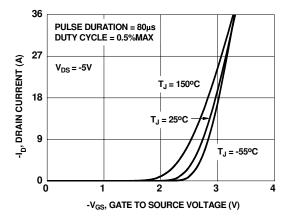


Figure 5. Transfer Characteristics

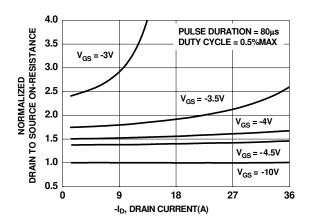


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

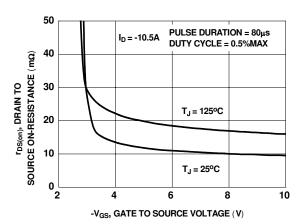


Figure 4. On-Resistance vs Gate to Source Voltage

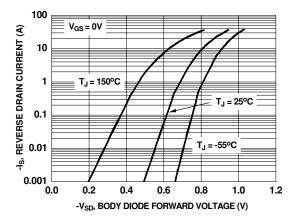


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

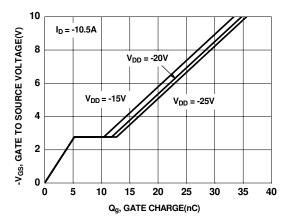


Figure 7. Gate Charge Characteristics

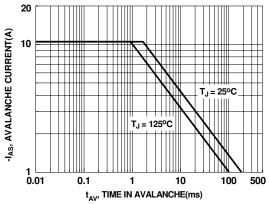


Figure 9. Unclamped Inductive Switching Capability

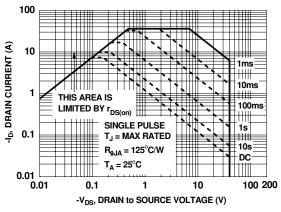


Figure 11. Forward Bias Safe Operating Area

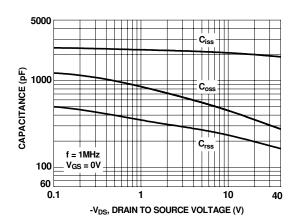


Figure 8. Capacitance vs Drain to Source Voltage

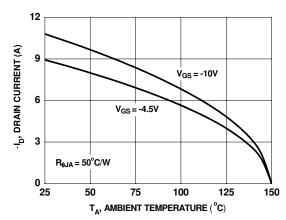


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

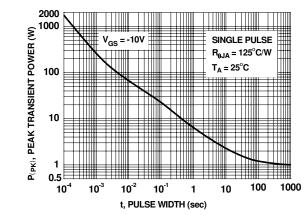


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

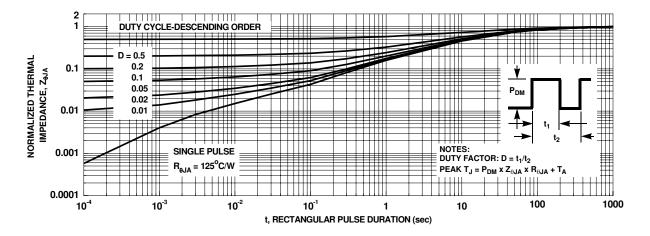
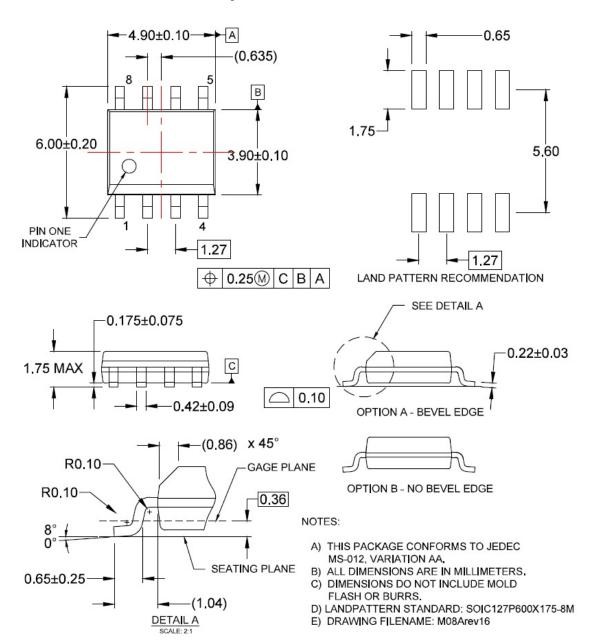


Figure 13. Transient Thermal Response Curve

## **Dimensional Outline and Pad Layout**



ON Semiconductor and the ON Logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other

countries.

ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="https://www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or

standards, regardless of any support or applications information provided by
ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative